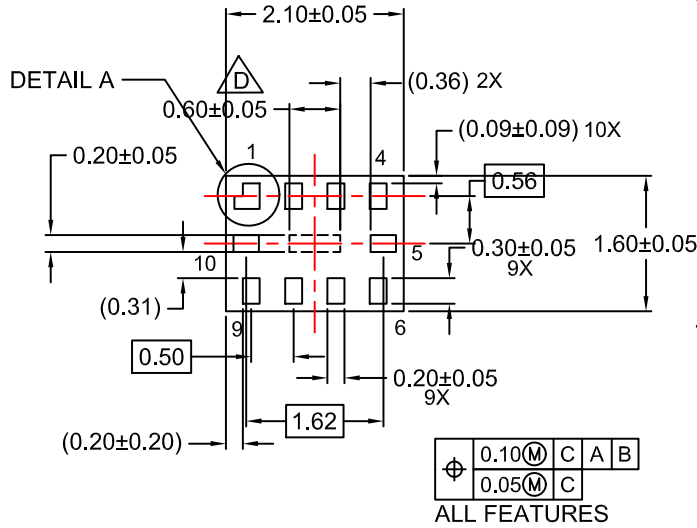
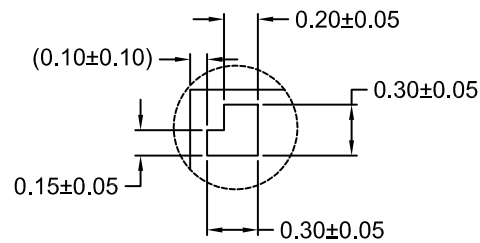
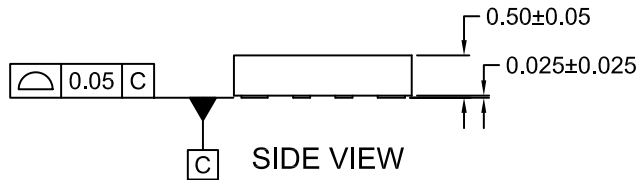
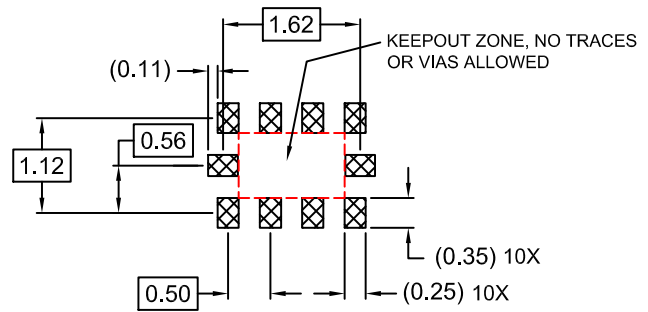
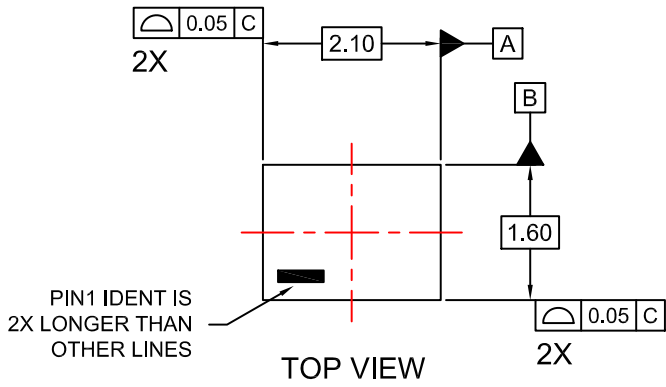




**UQFN10 1.6X2.1, 0.5P**  
CASE 523AZ  
ISSUE O

DATE 31 AUG 2016



- NOTES:**
- A. PACKAGE CONFORMS TO JEDEC REGISTRATION MO-255, VARIATION UABD .
  - B. DIMENSIONS ARE IN MILLIMETERS.
  - C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
  - D. PRESENCE OF CENTER PAD IS PACKAGE SUPPLIER DEPENDENT. IF PRESENT IT IS NOT INTENDED TO BE SOLDERED AND HAS A BLACK OXIDE FINISH.
  - E. DIMENSIONS WITHIN ( ) ARE UNCONTROLLED

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